

International Committee of the Decorative Laminates Industry

**Technical Leaflet** 

## Gluing Table for High Pressure Laminates (HPL)

May, 2013

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## Preface

Decorative laminate (HPL = High-pressure laminate) can look back on a long tradition of use and represents an extremely robust, modern and highly decorative surface material. It is a ubiquitous part of daily life, mostly making an appearance as part of a composite material together with derived timber products such as chipboard. Having been developed more than 60 years ago, decorative laminate sheets now have more areas of application than ever before. One reason for this is the extreme durability of decorative laminate boards. No other finishing material can offer anything like the same levels of resilience. The European Standard EN 438 stipulates well over 20 properties which decorative laminate surfaces must fulfill. On the other hand, the extensive variety of attractive finishes decorative laminate panels can be supplied which makes them extremely attractive, provides flexibility of use and enables a wide range of base materials to be deployed. Added to this, the innovative further development of decorative laminate as a material has brought with it a constant expansion of the possible areas of application.

This Information Data Sheet "Gluing table for decorative high pressure laminates (HPL)" gives an overview and valuable recommendations about adhesives for decorative high pressure laminates. The technical commission of the ICDLI compiled this Data Sheet to the best of its knowledge. No responsibility is taken for the up-to-date-ness, accuracy, completeness or quality of the details provided.

This Data Sheet replaces the one on the same subject from 2008.

This document makes no claim of completion regarding listing the full details of any standards referred to in the text.

All information is based on the current state of technical knowledge, but it does not constitute any form of liability. It is the personal responsibility of the user of the products described in this information leaflet to comply with the appropriate laws and regulations.

For more than 50 years the ICDLI has been the international representative of the interests of European laminate manufacturers. Further information about the ICDLI and the data sheets published up to now can be found at <a href="http://www.icdli.com">www.icdli.com</a>.

This application was compiled by the International Committee of the Decorative Laminates Industry. It considers the conditions of application technology in the European countries. If you have further questions, please contact us:

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Adhesives			Dispersion-Adhesives		Condensation-Adbesives			Contact-Adhesives		Reaction Adhesives	Hot-melt-type adhes		ives					
Substrates		N o	1 part PVAc	2 part PVAc	UF-glue /UF-glue with app.10 % fillers	MUF / MUPF- glue	Phenol- Resorcinolg	lue	w ithout cataly st	with catalyst	PUR-, Polyester-, Epoxid-adhesive	EVA Ethy len-Viny l- Acetate	PA / PO Poly amide- Poly olefine	PUR Poly urethane				
Classification acc. EN 204 / EN 205 Temperature Resistance [°C]			D2 / D3 / D4 - 20 to +100	D3 / D4 - 20 to +120	D2 / D3	D3 - 20 to +150	D3 / D4		no classification ac - 20 to + 70	- 20 to + 100	D3 / D4 - 20 to +100	classification - 20 to +80	- 20 to +100	D3 / D4 - 20 to +120				
	Chipboard	Chipboards 1 adhesive applied: 80 - 200 g/m <sup>2</sup> on HPL or substrate			adhesive applied: adhesive   90 - 150g/m <sup>2</sup> applied:   00 - 150g/m <sup>2</sup> 100 - 180 g/m <sup>2</sup> on HPL or substrate on HPL or		adhesiv e applied: 150 - 200g/m <sup>2</sup>			•								
strates	Ply w ood and blockboard		2	open time:		open time:		substrate					adhesive applied: 80 - 150 g/m <sup>2</sup> on HPL or substrate pressure: nip rolls		adhesive applied:			
Fibreboards MDF, HDF, hardboards Solid timber			3	2 - 3	0 Min. sure:	5 - 15 Min. pressure:		2 - 15 Min. pressure: 3 - 5 bar		open time: depends on adhesive type and spread					60 - 100 g/m <sup>2</sup> on HPL or substrate			
			4	app. 2 press temperat	- 5 bar ture/ press time:	app. 3 - 5 bar press temperature/ press time:		press temperatu press time	re/ e:	pressure an momentary pre bonding strength d	momentary pressure is sufficient bonding strength depends on pressure		adhesive application temperature: 160 - 220 °C		pressure: nip rolls			
S	Pay attention to differences		5	20 °C / 2 40 °C / 2 60 °C / 3	2 - 60 Min. 2 - 12 Min. 2 - 6 Min.	40 °C / 30 - 43 Min. 60°C / 10 - 12 Min. 80°C / app. 5 Min.		open time and press time		load press temperature: at least +20 °C					adhesiv e application			
loneycomt		in thickness between frame &		80 °C /	1 - 3 Min.	100°C /app. 1 Min.		depends o catalyst sys	on tem						temperature: 120 - 160 °C			
т	Alu-honey combs	r-honey combs core, e.g., reduce pressure										adhesive applied: 150 - 200 g/m <sup>2</sup> on HPL or	not applicable					
Polystyrene foam				not applicable							substrate open time : depends on		priouble					
Foams	Phenolic foam	ower press	8									adhesive type pressure:						
	PU foam									not applicable		store flat			adhesive			
	PVC - foam		10	adhesiye	desive applied -				press temperature/ press			applied: 80 - 120 g/m <sup>2</sup> on HPI						
	Ex panded Mica (Vermiculite)		11	110-150 g/m subs open time:	<sup>2</sup> on HPL or strate max 10 Min.				time:depends on adhesive type and catalyst (in			pressure: nip rolls						
S	Calcium-Silicate Boards		12	pressure: app.2-5 bar press temperature/press-time: 20°C / 30 Min. Surface shuold be primed See lines 1 - 5								case of metals pretreatment of surface is essential)	mainly for edge bending see lines 1-5		adhesive application			
leral Board	Fibre-Cement Boards	Fibre-Cement Boards			lisshia										120 - 160 °C			
Min	Cement-bonded Chipboard	Cement-bonded Chipboard Gy psum Plaster Board 15 see lines 1 - 5		1	14	not ap	рпсавте	see lines 11 - 13										
	Gypsum Plaster Board			es 1 - 5	see lines 1 - 5 see lines 11 - 13		applicable											
Gy psum-Fibre Board			16	see line				s 11 - 12										
Metal			17	Pretreat surface a esse				Pretreatmer surface absol essential	it of lutely	see lines 1-5			not applicable		pretreatment of surface absolutely essential			
HPL			18												applicable			
	Processir	low er				Cotolystanssat							1		1			
rfaces	Block press (cold)	ress (cold) surface pressure adhesive coating applied by four-roller catalyst-precoat; adhesive coating applied by four-roller adhesive coating adhesive coating adhesi				Cataly st-prem	ix ed;	;	adhesiv e coating									
ting flat su	opening press (cold, warm, hot)	20		four-roller, glue-spreader or filling		Catalyst-precoat or Catalyst - premixed; adhesive coating applied		adhesive coating applied by four-		adhesive coating applied by spraying or spreading		by manual application						
PL-lamina	Short-cycle press (warm, hot)	/cle press 21 by four-roller or filling roller or filling					ng											
Ŧ	Continous belt press (warm, hot)		22	see line 20														
ninating	pressed in matched moulds		23	only applicable to big curved shapes in two						o dimensions								
HPL-Ia	Membrane- (vacuum)-press		24															
ning	stationary	see technical	25		applicable													
Postform	continous	leaflet "Post- formable HPL"	26	applicable	D4 problematic and process related													
ending	stationary	27 cold-pressing or usage of strip heating					appl	licable	applicable	able precoated edges no								
Edge-b	continous		28	adhesiv e reac	adhesive reactivating process							hotmelt-coating on substrate or edging mate						

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